

DAC7545

CMOS 12-Bit Multiplying DIGITAL-TO-ANALOG CONVERTER Microprocessor Compatible

FEATURES

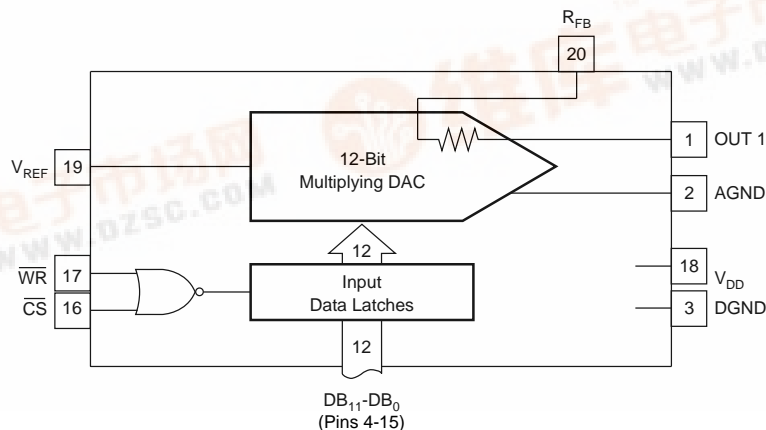
- FOUR-QUADRANT MULTIPLICATION
- LOW GAIN TC: 2ppm/°C typ
- MONOTONICITY GUARANTEED OVER TEMPERATURE
- SINGLE 5V TO 15V SUPPLY
- TTL/CMOS LOGIC COMPATIBLE
- LOW OUTPUT LEAKAGE: 10nA max
- LOW OUTPUT CAPACITANCE: 70pF max
- DIRECT REPLACEMENT FOR AD7545, PM-7545

DESCRIPTION

The DAC7545 is a low-cost CMOS, 12-bit four-quadrant multiplying, digital-to-analog converter with input data latches. The input data is loaded into the DAC as a 12-bit data word. The data flows through to the DAC when both the chip select (\overline{CS}) and the write (\overline{WR}) pins are at a logic low.

Laser-trimmed thin-film resistors and excellent CMOS voltage switches provide true 12-bit integral and differential linearity. The device operates on a single +5V to +15V supply and is available in 20-pin plastic DIP or 20-lead plastic SOIC packages. Devices are specified over the commercial.

The DAC7545 is well suited for battery or other low power applications because the power dissipation is less than 0.5mW when used with CMOS logic inputs and $V_{DD} = +5V$.



SPECIFICATIONS

ELECTRICAL

$V_{REF} = +10V$, $V_{OUT1} = 0V$, $ACOM = DCOM$, unless otherwise specified.

PARAMETER	GRADE	DAC7545				UNITS	TEST CONDITIONS/COMMENTS
		$V_{DD} = +5V$		$V_{DD} = +15V$			
		$T_A = +25^\circ C$	$T_{MAX} - T_{MIN}^{(1)}$	$T_A = +25^\circ C$	$T_{MAX} - T_{MIN}^{(1)}$		
STATIC PERFORMANCE							
Resolution	All	12	12	12	12	Bits	
Accuracy	J	± 2	± 2	± 2	± 2	LSB	
	K	± 1	± 1	± 1	± 1	LSB	
	L	$\pm 1/2$	$\pm 1/2$	$\pm 1/2$	$\pm 1/2$	LSB	
	GL	$\pm 1/2$	$\pm 1/2$	$\pm 1/2$	$\pm 1/2$	LSB	
	J	± 4	± 4	± 4	± 4	LSB	10-Bit Monotonic, T_{MIN} to T_{MAX}
Differential Nonlinearity	K	± 1	± 1	± 1	± 1	LSB	10-Bit Monotonic, T_{MIN} to T_{MAX}
	L	± 1	± 1	± 1	± 1	LSB	12-Bit Monotonic, T_{MIN} to T_{MAX}
	GL	± 1	± 1	± 1	± 1	LSB	12-Bit Monotonic, T_{MIN} to T_{MAX}
	J	± 20	± 20	± 25	± 25	LSB	D/A register loaded with FFF_H .
Gain Error (with internal R_{FB}) ⁽²⁾	K	± 10	± 10	± 15	± 15	LSB	Gain error is adjustable using the circuits in Figures 2 and 3.
	L	± 5	± 6	± 10	± 10	LSB	
	GL	± 2	± 3	± 6	± 7	LSB	
	J	± 5	± 5	± 10	± 10	ppm/ $^\circ C$	
Gain Temperature Coefficient ⁽³⁾ ($\Delta Gain/\Delta Temperature$)	All	± 5	± 5	± 10	± 10	ppm/ $^\circ C$	Typical value is 2ppm/ $^\circ C$
DC Supply Rejection ⁽³⁾ ($\Delta Gain/\Delta V_{DD}$)	All	0.015	0.03	0.01	0.02	%/%	$\Delta V_{DD} \pm 5\%$
Output Leakage Current at Out 1	J, K, L, GL	10	50	10	50	nA	$DB_0 - DB_{11} = 0V$; \overline{WR} , $\overline{CS} = 0V$
DYNAMIC PERFORMANCE							
Current Settling Time ⁽³⁾	All	2	2	2	2	μs	To 1/2LSB. Out ₁ Load = 100 Ω DAC output measured from falling edge of \overline{WR} . $\overline{CS} = 0V$
Propagation Delay ⁽³⁾ (from digital input change to 90% of final analog output)	All			250		ns	Out ₁ Load = 100 Ω . $C_{EXT} = 13pF^{(4)}$
Glitch Energy	All	400		250		nV-s ⁽⁵⁾	$V_{REF} = ACOM$
AC Feedback at I _{OUT1}	All	5	5	5	5	mVp-p ⁽⁵⁾	$V_{REF} = \pm 10V$, 10kHz Sine Wave
REFERENCE INPUT							
Input Resistance (pin 19 to AGND)	All	7 25	7 25	7 25	7 25	k $\Omega^{(6)}$ k Ω	Input resistance TC = 300ppm/ $^\circ C^{(5)}$
AC OUTPUTS							
Output Capacitance ⁽³⁾ : C _{OUT1}	All	70	70	70	70	pF	$DB_0 - DB_{11} = 0V$; \overline{WR} , $\overline{CS} = 0V$
C _{OUT2}	All	200	200	200	200	pF	$DB_0 - DB_{11} = V_{DD}$; \overline{WR} , $\overline{CS} = 0V$
DIGITAL INPUTS							
V _{IH} (Input HIGH Voltage)	All	2.4	2.4	13.5	13.5	V ⁽⁶⁾	
V _{IL} (Input LOW Voltage)	All	0.8	0.8	1.5	1.5	V	
I _{IN} (Input Current) ⁽⁷⁾	All	± 1	± 10	± 1	± 10	μA	$V_{IN} = 0$ or V_{DD}
Input Capacitance ⁽³⁾ : $DB_0 - DB_{11}$ \overline{WR} , \overline{CS}	All	5	5	5	5	pF	$V_{IN} = 0V$
	All	20	20	20	20	pF	$V_{IN} = 0V$
SWITCHING CHARACTERISTICS⁽⁸⁾							
Chip Select to Write Setup Time, t _{CS}	All	280	380	180	200	ns ⁽⁶⁾	See Timing Diagram
		200	270	120	150	ns ⁽⁵⁾	
Chip Select to Write Hold Time, t _{CH}	All	0	0	0	0	ns ⁽⁶⁾	t _{CS} \geq t _{WR} , t _{CH} \geq 0
Write Pulse Width, t _{WR}	All	250	400	160	240	ns ⁽⁶⁾	
		175	280	100	170	ns ⁽⁵⁾	
Data Setup Time, t _{DS}	All	140	210	90	120	ns ⁽⁶⁾	
Data Hold Time, t _{DH}		100	150	60	80	ns ⁽⁵⁾	
	All	10	10	10	10	ns ⁽⁶⁾	
POWER SUPPLY, I_{DD}							
	All	2	2	2	2	mA	All Digital Inputs V _{IL} or V _{IH}
	All	100	500	100	500	μA	All Digital Inputs 0V or V _{DD}
	All	10	10	10	10	$\mu A^{(5)}$	All Digital Inputs 0V or V _{DD}

NOTES: (1) Temperature ranges—J, K, L, GL: $-40^\circ C$ to $+85^\circ C$. (2) This includes the effect of 5ppm max. gain TC. (3) Guaranteed but not tested. (4) $DB_0 - DB_{11} = 0V$ to V_{DD} or V_{DD} to $0V$. (5) Typical. (6) Minimum. (7) Logic inputs are MOS gates. Typical input current ($+25^\circ C$) is less than 1nA. (8) Sample tested at $+25^\circ C$ to ensure compliance.

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ABSOLUTE MAXIMUM RATINGS⁽¹⁾

T_A = +25°C, unless otherwise noted.

V _{DD} to DGND -0.3V, +17
Digital Input to DGND -0.3V, V _{DD}
V _{RFB} , V _{REF} , to DGND ±25V
V _{PIN 1} to DGND -0.3V, V _{DD}
AGND to DGND -0.3V, V _{DD}
Power Dissipation: Any Package to +75°C 450mW
Derates above +75°C by 6mW/°C
Operating Temperature:	
Commercial J, K, L, GL -40°C to +85°C
Storage Temperature -65°C to +150°C
Lead Temperature (soldering, 10s) +300°C

NOTE: (1) Stresses above those listed above may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other condition above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

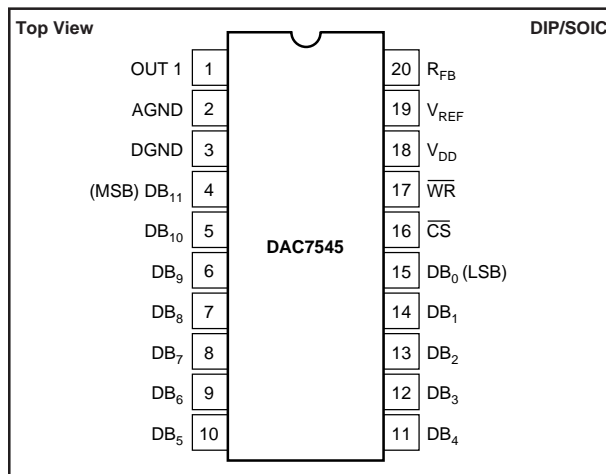


ELECTROSTATIC DISCHARGE SENSITIVITY

Any integral circuit can be damaged by ESD. Burr-Brown recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet published specifications.

PIN CONNECTIONS



PACKAGE INFORMATION

PRODUCT	PACKAGE	PACKAGE DRAWING NUMBER ⁽¹⁾
DAC7545JP	20-Pin PDIP	222
DAC7545KP	20-Pin PDIP	222
DAC7545LP	20-Pin PDIP	222
DAC7545GLP	20-Pin PDIP	222
DAC7545JU	20-Pin SOIC	221
DAC7545KU	20-Pin SOIC	221
DAC7545LU	20-Pin SOIC	221
DAC7545GLU	20-Pin SOIC	221

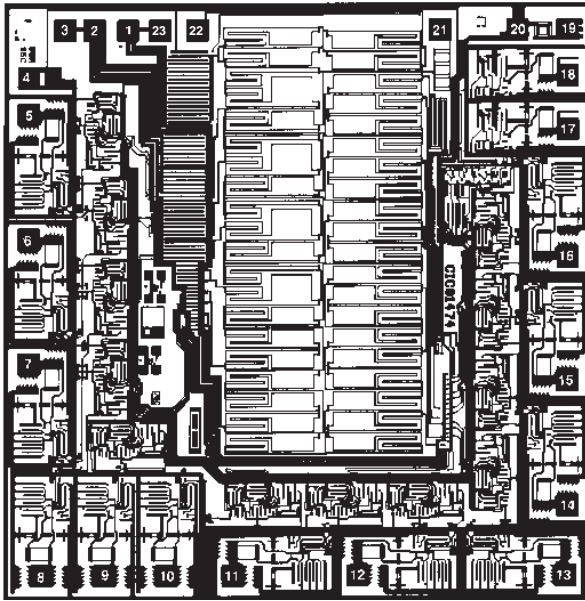
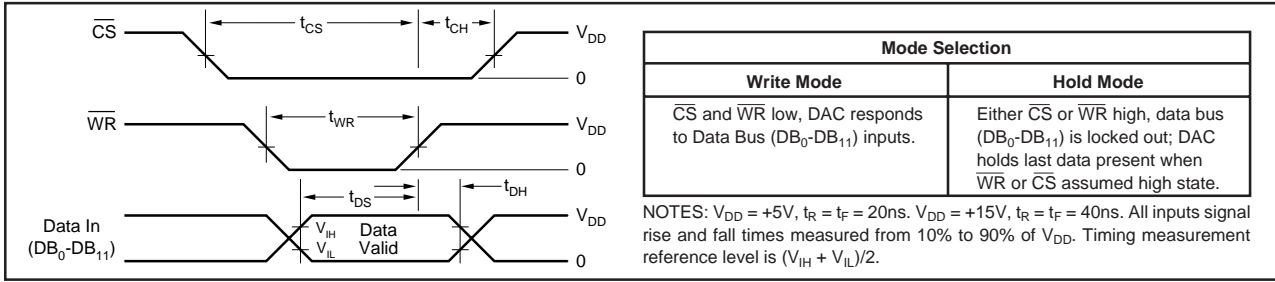
NOTE: (1) For detailed drawing and dimension table, please see end of data sheet, or Appendix C of Burr-Brown IC Data Book.

ORDERING INFORMATION

PRODUCT	PACKAGE	TEMPERATURE RANGE	RELATIVE ACCURACY (LSB)	GAIN ERROR (LSB) V _{DD} = +5V
DAC7545JP	Plastic DIP	-40°C to +85°C	±2	±20
DAC7545KP	Plastic DIP	-40°C to +85°C	±1	±10
DAC7545LP	Plastic DIP	-40°C to +85°C	±1/2	±5
DAC7545GLP	Plastic DIP	-40°C to +85°C	±1/2	±2
DAC7545JU	Plastic SOIC	-40°C to +85°C	±2	±20
DAC7545KU	Plastic SOIC	-40°C to +85°C	±1	±10
DAC7545LU	Plastic SOIC	-40°C to +85°C	±1/2	±5
DAC7545GLU	Plastic SOIC	-40°C to +85°C	±1/2	±2



WRITE CYCLE TIMING DIAGRAM



DAC7545 DIE TOPOGRAPHY

PAD	FUNCTION	PAD	FUNCTION
1	OUT 1	13	DB_3
2	AGND	14	DB_2
3	AGND	15	DB_1 (LSB)
4	DGND	16	DB_0
5	DB_{11}	17	\overline{CS}
6	DB_{10}	18	\overline{WR}
7	DB_9	19	\overline{XYR}
8	DB_8	20	V_{DD}
9	DB_7	21	V_{REF}
10	DB_6	22	R_{FB}
11	DB_5	23	OUT_1
12	DB_4		

Substrate Bias: Isolated. NC: No Connection

MECHANICAL INFORMATION

	MILS (0.001")	MILLIMETERS
Die Size	136 x 134 ± 5	3.45 x 3.40 ± 0.13
Die Thickness	20 ± 3	0.51 ± 0.08
Min. Pad Size	4 x 4	0.10 x 0.10
Metalization	Aluminum	

DISCUSSION OF SPECIFICATIONS

Relative Accuracy

This term (also known as end point linearity) describes the transfer function of analog output to digital input code. Relative accuracy describes the deviation from a straight line after zero and full scale have been adjusted.

Differential Nonlinearity

Differential nonlinearity is the deviation from an ideal 1LSB change in the output, for adjacent input code changes. A differential nonlinearity specification of 1LSB guarantees monotonicity.

Gain Error

Gain error is the difference in measure of full-scale output versus the ideal DAC output. The ideal output for the DAC7545 is $-(4095/4096)(V_{REF})$. Gain error may be adjusted to zero using external trims as shown in the applications section.

Output Leakage Current

The current which appears at OUT 1 with the DAC loaded with all zeros.

Multiplying Feedthrough Error

The AC output error due to capacitive feedthrough from V_{REF} to OUT 1 with the DAC loaded with all zeros. This test is performed using a 10kHz sine wave.

Output Current Settling Time

The time required for the output to settle within $\pm 0.5LSB$ of final value from a change in code of all zeros to all ones, or all ones to all zeros.



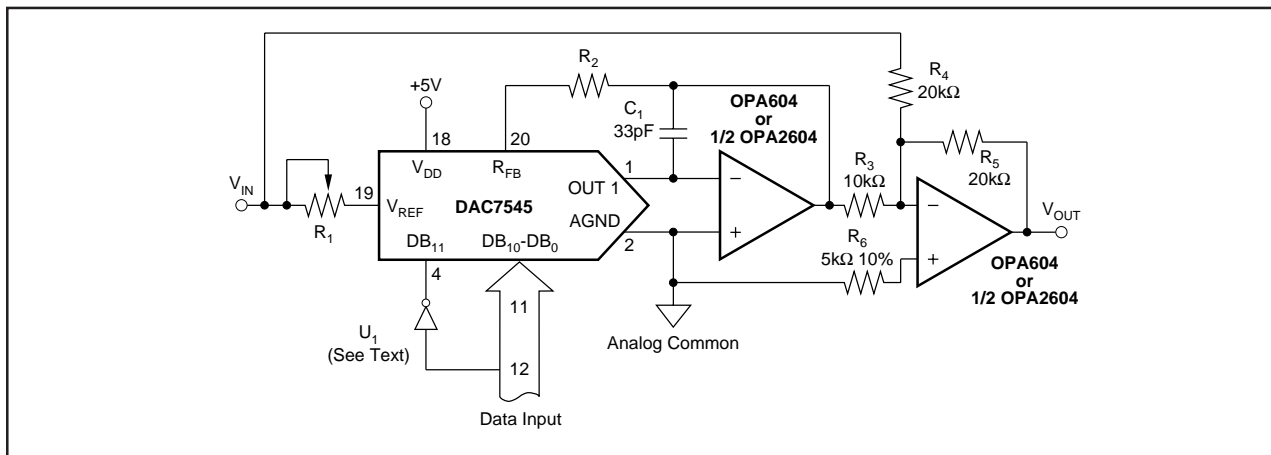


FIGURE 3. Bipolar Operation (Two's Complement Code).

BIPOLAR OPERATION

Figure 3 and Table II illustrate the recommended circuit and code relationship for bipolar operation. The D/A function itself uses offset binary code. The inverter, U_1 , on the MSB line converts two's complement input code to offset binary code. If the inversion is done in software, U_1 may be omitted.

R_3 , R_4 , and R_5 must match within 0.01% and should be the same type of resistors (preferably wire-wound or metal foil), so that their temperature coefficients match. Mismatch of R_3 value to R_4 causes both offset and full-scale error. Mismatch of R_5 to R_4 and R_3 causes full-scale error.

DATA INPUT		ANALOG OUTPUT
MSB	LSB	
0111	1111 1111	$+V_{IN}$ (2047/2048)
0000	0000 0001	$+V_{IN}$ (1/2048)
0000	0000 0000	0 V
1111	1111 1111	$-V_{IN}$ (1/2048)
1000	0000 0000	$-V_{IN}$ (2048/2048)

TABLE II. Two's Complement Code Table for Circuit of Figure 3.

DIGITALLY CONTROLLED GAIN BLOCK

Figure 4 shows a circuit for digitally controlled gain block. The feedback for the op amp is made up of the FET switch and the R-2R ladder. The input resistor to the gain block is the R_{FB} of the DAC7545. Since the FET switch is in the feedback loop, a "zero code" into the DAC will result in the op amp having no feedback, and a saturated op amp output.

APPLICATIONS HINTS

CMOS DACs, such as the DAC7545, exhibit a code-dependent out resistance. The effect of this is a code-dependent differential nonlinearity at the amplifier output which depends on the offset voltage, V_{OS} , of the amplifier. Thus linearity depends upon the potential of OUT 1 and AGND being exactly equal to each other. Usually the DAC is

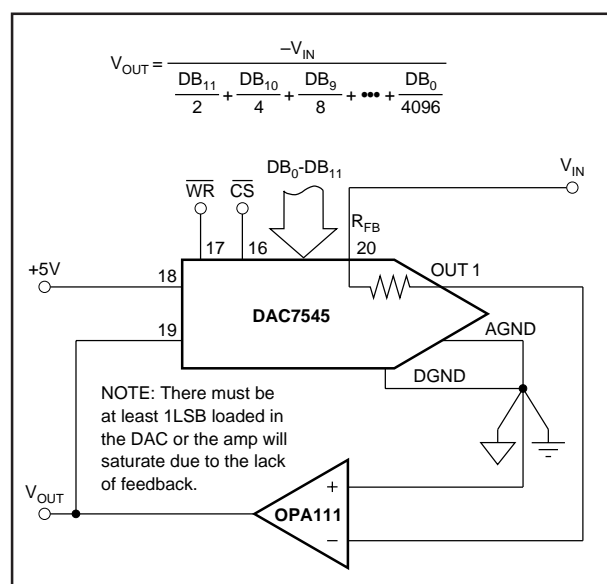


FIGURE 4. Digitally Controlled Gain Block.

connected to an external op amp with its noninverting input connected to AGND. The op amp selected should have a low input bias current and low V_{OS} and V_{OS} drift over temperature. The op amp offset voltage should be less than $(25 \times 10^{-6})(V_{REF})$ over operating conditions. Suitable op amps are the Burr-Brown OPA37 and the OPA627 for fixed reference applications and low bandwidth requirement. The OPA37 has low V_{OS} and will not require an offset trim. For wide bandwidth, high slew rate, or fast settling applications, the Burr-Brown OPA604 or 1/2 OPA2604 are recommended.

Unused digital inputs should be connected to V_{DD} or to DGND. This prevents noise from triggering the high impedance digital input. It is suggested that the unused digital inputs also be given a path to ground or V_{DD} through a 1MΩ resistor to prevent the accumulation of static charge if the PC card is unplugged from the system. In addition, in systems where the AGND to DGND connection is on a backplane, it is recommended that two diodes be connected in inverse parallel between AGND and DGND.

INTERFACING TO MICROPROCESSORS

The DAC7545 can be directly interfaced to either an 8- or 16-bit microprocessor through its 12-bit wide data latch using the \overline{CS} and \overline{WR} controls.

An 8-bit processor interface is shown in Figure 5. It uses two memory addresses, one for the lower 8 bits and one for the upper 4 bits of data into the DAC via the latch.

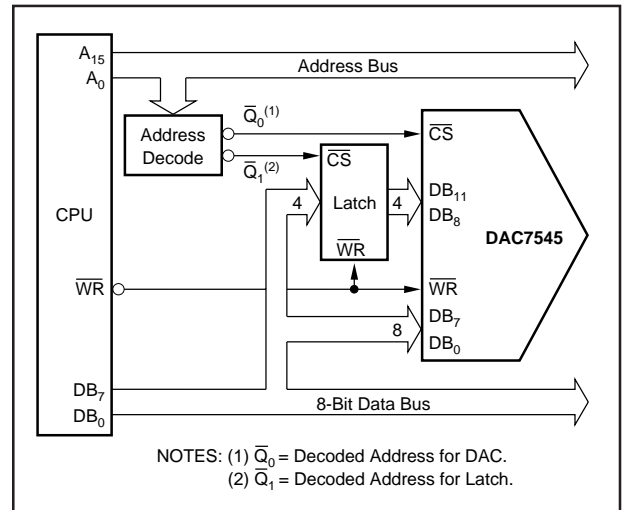


FIGURE 5. 8-Bit Processor Interface.

